

# The 2nd Taiwan-Japan Joint Symposium in Taiwan

Chairman: Weileun Fang (National Tsing Hua Univ.)  
 Co-Chairman: Sheng-Shian Li (National Tsing Hua Univ.)  
 Co-chairman: T. Hiramoto (Univ. of Tokyo)  
 Workshop chair: M. Goto (NHK)  
 Research meeting chair: S. Hata (Nagoya Univ.)

The study group of the Integrated MEMS of the Japan Society of Applied Physics (JSAP) will hold 2nd Taiwan-Japan Joint Symposium in Taiwan on 31<sup>st</sup> May – 1<sup>st</sup> June 2018 during Nano Engineering and Microsystem Technology Conference, which is domestic conference in Taiwan on 1<sup>st</sup> June – 2<sup>nd</sup> June 2018 (<http://www.nma.tw/>). The purpose of this joint symposium is carried out as the interchange between Taiwan and Japan, which is following the 1<sup>st</sup> joint symposium held at Hirado, Japan in 2016.

In the tenth anniversary of the study group of the Integrated MEMS, we plan the 2nd Taiwan-Japan Joint Symposium as the joint of the workshop and meeting at the study group. Based on the contents of the workshop which is comprised of the tour and poster session, the program includes the technical tour in Hsinchu area on the first day and joint symposium on the second day. The joint symposium consists of plenary talk, four invited talks, regular poster session, and banquet.

In the plenary talk and the invited talks, you could have the valuable opportunity to hear the state-of-the art talks with the IoT device, the trend of LSI, material for CMOS-MEMS, the integrated MEMS approach, and CMOS-MEMS technology.

Please submit your paper and join the symposium. We are looking forward to seeing you in Taiwan.

## ● Schedule & Program

[Japan-Taiwan Young Researcher mini-workshop] Thursday, May 31<sup>st</sup> 2018

Venue: R108, Engineering Building I, National Tsing Hua Univ.

Chair: Prof. Weileun Fang

- ◆ 9:30-9:40 Opening & U. of Tokyo – NTHU MOU Ceremony
- ◆ 9:40-11:00 Presentations by young faculty members from Taiwan and Japan (planning 4 from Taiwan and 4 from Japan)
- ◆ 11:00-11:30 Prof. Weileun Fang (PME National Tsing Hua Univ.), "MEMS/Sensors Ecosystems in Taiwan"

[Technical tour] Thursday, May 31<sup>st</sup> 2018, Hsinchu area

- ◆ 11:30-13:00 Lunch in campus restaurant (<https://www.facebook.com/Socratescoffe/>).
- ◆ 13:00-18:00 The technical tour schedule in Hsinchu area:
  - NDL (National Nano Device Laboratories) (<http://www.ndl.org.tw/>)
  - CIC (Chip Implementation Center) (<https://www.cic.org.tw/english/index.jsp>)
  - ITRC (Instrument Technology Research Center) (<http://www.itrc.narl.org.tw/>)
  - TDK-InvenSense
  - APM (Asia Pacific Microsystems)
- ◆ 18:00-20:00 Banquet in Pengyuan (Chinese restaurant) (reservations required)
- ◆ 20:00-21:00 Move to Taipei by shuttle bus (capacity of 40 seats, reservations required)

[Joint symposium] Friday, June 1<sup>st</sup> 2018, Taipei area

- ◆ 11:20-12:00 Plenary talk  
Prof. Hiroshi Toshiyoshi (Univ. of Tokyo),  
"MEMS Vibrational Energy Harvester for IoT Wireless Sensor Applications"
- ◆ 12:00-13:30 Break
- ◆ 13:30-14:30 Poster session: Short presentation  
Each poster presenter will give 2 minutes short presentation for the poster.
- ◆ 14:30-15:50 Japan-Taiwan joint session
  - 14:30-14:50 Dr. Ralph Tsung-Hsien Lin (TDK InvenSense Inc.),  
"Miniaturized Pressure Sensor Technology through Integrated MEMS Approach"
  - 14:50-15:10 Prof. Toshiro Hiramoto (Univ. of Tokyo) ,  
"Advanced CMOS Devices for VLSI: Present Status and Roadmap"
  - 15:10-15:30 Prof. Masato Sone (Tokyo Inst. of Tech.),  
"Characteristics of Electroplated Gold Material with Multilayer Metal Technology for CMOS-MEMS Accelerometer"
  - 15:30-15:50 Prof. Tim Chih-Ting Lin (National Taiwan University),  
"CMOS-NEMS Integration for Bio and Chemical Sensing"

- ◆ 15:50-16:00 Break
  - ◆ 16:00-17:30 Poster session
  - ◆ 18:30-20:00 Banquet Fullon Hotel Taipei East (reservations required)
- Paper submission: Authors should submit one-page summary for poster session. Submissions will be accepted until May 17<sup>th</sup> 2018. Paper should include your original research work. Technical introduction from the company is also acceptable.
  - Participation application
    - The technical tour, reception, and shuttle bus: please apply to a secretariat (following e-mail address) by May 15<sup>th</sup> 2018.
    - Joint symposium and banquet: please apply to a secretariat (following e-mail address) by May 24<sup>th</sup> 2018.
  - Registration fee: Workshop member: no charge, Non-member: 5000 Japanese yen (You can be a member if you apply.)
  - Poster presentation: Short presentation file (PowerPoint, 2 min.) and poster (size: within poster board of 87cm (W) × 157cm (H)) should be prepared.
  - Excellent poster award: Excellent poster award will be given to the selected paper.
  - Contact information, Secretariat e-mail: [integmems@lsi.pi.titech.ac.jp](mailto:integmems@lsi.pi.titech.ac.jp)  
 When you apply the symposium, please include the following information in e-mail.  
 (Deadline: May 15<sup>th</sup> for the technical tour / May 24<sup>th</sup> for the joint symposium)  
 Name / Affiliation / E-mail address / Phone number / Mailing address /  
 Member information (member/non-member/student) /  
 Attendance to technical tour (Yes/No) / Attendance to 1st-day reception (Yes/No) / Shuttle bus (Yes/No)  
 Attendance to 2nd-day banquet (Yes/No)
  - Accommodation  
 Fullon Hotel Taipei East provides special offers to the seminar participants.  
 The special price starts from NTD 2800.  
 Please fill in the application form and send it to secretariat in Taiwan before May 18<sup>th</sup> 2018.  
 Regular price will be applied if the reservations is made after May 18<sup>th</sup>.